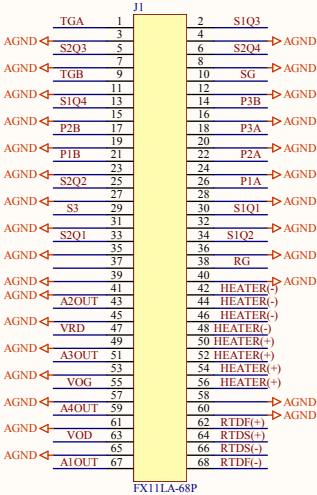
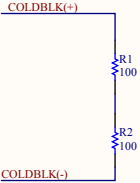
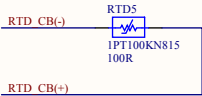
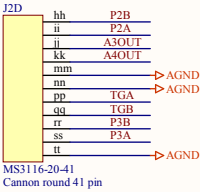
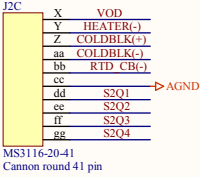
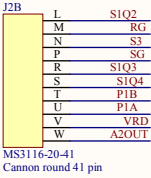
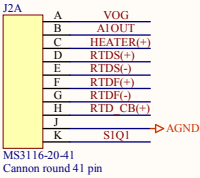


CDO	DRIVE
1	S1Q1
2	S1Q2
3	S1Q3
4	S1Q4
5	S2Q1
6	S2Q2
7	S2Q3
8	S2Q4
9	S3
10	RG
11	SG
12	P1A
13	P1B
14	P2A
15	P2B
16	P3A
17	P3B
18	TGA
19	TGB



Title			
SCH, FLEX CIRCUIT, SINISTRO			
Size	Number	Revision	
B	780-00034	2	
Date:	7/6/2011	Sheet	of
File:	U:\Altum Projects\780-00034 rev2 Flex Circuit\Sinistro.SchDoc		

NOTES (UNLESS OTHERWISE SPECIFIED):

GENERAL

- 1) RIGID-FLEX PORTION IS 6 LAYER
- 2) FLEX PORTION IS 4 LAYER
- 3) NO SOLDER MASK OR OVERLAY LAYERS
- 4)
- 5) THE PHOTO TOOL SHALL NOT BE COMPENSATED WITHOUT PRIOR ENGINEERING APPROVAL.  
PCB DESIGNER: RICH LOBOLL PH (805) 880-1621 FAX (805) 961-1792.

FABRICATION TOLERANCES

- 6) END PRODUCT CONDUCTOR WIDTHS AND PAD DIAMETERS SHALL NOT VARY MORE THAN 0.002" FROM THE 1:1 DIMENSIONS OF THE MASTER ARTWORK.
- 7) THE CONDUCTIVE PATTERN SHALL BE POSITIONED SO THAT THE LOCATION OF ANY PAD OR LAND SHALL BE WITHIN 0.005" DIAMETER TO THE TRUE POSITION OF THE HOLE IT CIRCUMSCRIBES.
- 8) ALL DRILL HOLE SIZES AND TOLERANCES APPLY AFTER PLATING.
- 9) THE MINIMUM ANNUAL RING SHALL BE 0.005".
- 10) BOW AND TWIST SHALL NOT EXCEED 0.010" PER INCH.
- 11) FOR PCB ROUTING DIMENSIONS:  $\pm 0.005"$   $\pm 0.005"$   $\pm 0.020"$

MATERIAL

- 12) RIGID SECTIONS  
BASE LAMINATE: ARLOX BSN (DO NOT USE BSN PRE-PREG)  
PRE-PREG: ARLOX 38N
- 13) FLEX SECTIONS  
FLEX LAMINATE: DUPONT PYRALUX APS111  
ADHESIVE: DUPONT PYRALUX LFO200

PLATING

- 14) ALL HOLES AND CONDUCTIVE SURFACES SHALL BE PLATED WITH A MINIMUM OF 0.001" COPPER.
- 15) ALL EXPOSED HOLES AND CONDUCTIVE SURFACES SHALL BE COATED WITH A GOLD IMMERSION PLATING TO PRESERVE SOLDERABILITY.

COATINGS

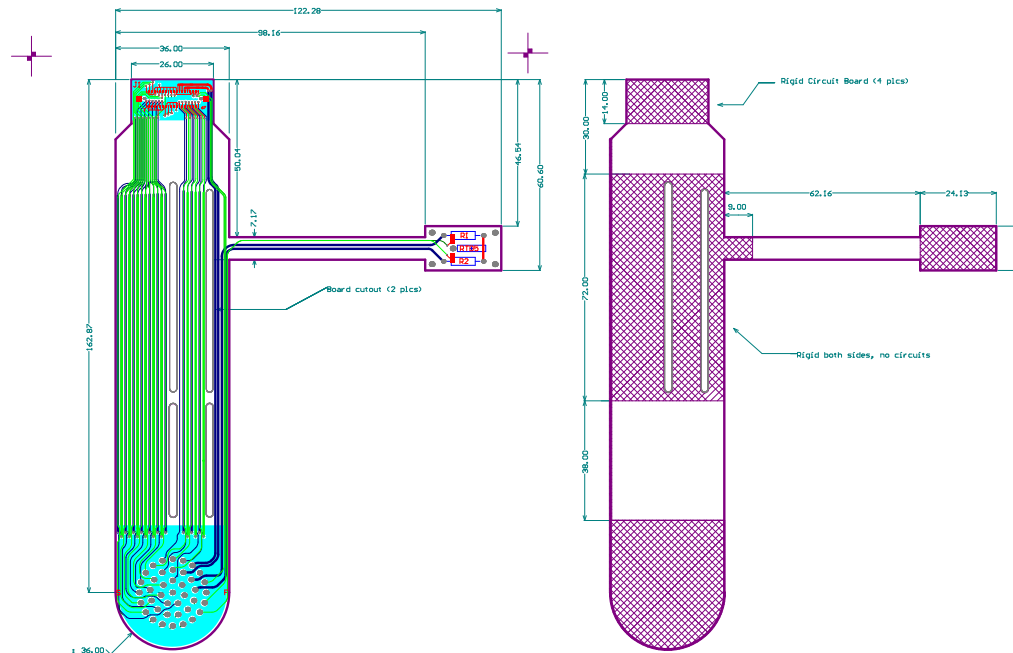
- 16) NO SOLDERMASK

MARKING

- 18) NO SILKSCREEN
- 19)
- 20)

ELECTRICAL TESTING

- 21) ALL BOARDS SHALL BE ELECTRICALLY TESTED TO THE SUPPLIED PC-D-356A NET LIST FOR CONTINUITY, OPENS AND SHORTS.



175-00030 rev2, Flex Circuit, Sinistro  
LAS CUMBRES OBSERVATORY 6/27/2011

\*GIL - BOPTOMAYER-SERBORT-BATA

Layer Stack Up Detail for: Flex\_Circuit.PcbDoc

Layer Name	Copper Cladding
Top Layer (*,GTL)	RIGID 1 oz.
Mid-Layer 1 (*,G1)	FLEX 1 oz.
Mid-Layer 2 (*,G2)	FLEX 1 oz.
Mid-Layer 3 (*,G3)	FLEX 1 oz.
Mid-Layer 4 (*,G4)	FLEX 1 oz.
Bottom Layer (*,GBL)	RIGID 1 oz.

PRIMARY PCB SPECIFICATIONS	
(REFER TO COMPLETE SPEC LISTING AT LEFT FOR FURTHER DETAILS)	
NUMBER OF LAYERS	— 6
FINISHED THICKNESS	— .062"
BASE MATERIAL	— SEE NOTES ABOVE
PLATING TYPE	— GOLD IMMERSION
SOLDER MASK COLOR	— NO SOLDER MASK

NOTICE  
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Las Cumbres Observatory Global Telescope Network		Las Cumbres Observatory, Inc. 6740 Cortona Dr. Goleta, CA 93117 www.lcogt.net	
DATE 6/27/2011	DRAWN Rich Loboll	DATE 6/27/2011	SCALE 1 : 1
DESIGNED 175-00030 rev2, FLEX CIRCUIT, SINISTRO		CHECKED 1 OF X	
DATE C	REV - GPT	DATE 2	SCALE 1 OF X